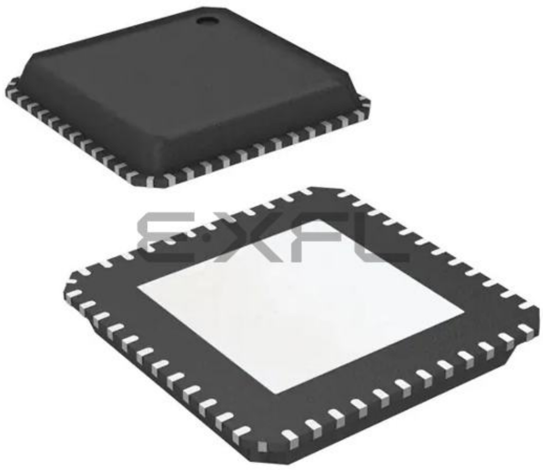

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, I²S, POR, PWM, WDT
Number of I/O	34
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	48-VFQFN Exposed Pad
Supplier Device Package	PG-VQFN-48-73
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xmc1401q048f0064aaxuma1

Features

CPU subsystem

- 32-bit ARM Cortex-M0 CPU Core
  - 0.84 DMIPS/MHz (Dhrystone 2.1) at 48 MHz
- Nested Vectored Interrupt Controller
- 64 interrupt nodes
- MATH coprocessor
  - 24-bit trigonometric calculation (CORDIC)
  - 32-bit divide operation
- 2x4 channels ERU for event interconnections

On-Chip Memories

- 8 Kbyte ROM
- 16 Kbyte SRAM (with parity)
- up to 200 Kbyte Flash (with ECC)

Supply, Reset and Clock

- 1.8 V to 5.5 V supply with power on reset and brownout detector
- On-chip clock monitor
- External crystal oscillator support (32 kHz and 4 to 20 MHz)
- Internal slow and fast oscillators without the need of PLL

System Control

- Window watchdog
- Real time clock module
- Pseudo random number generator

Communication Peripherals

- Four USIC channels, usable as
  - UART (up to 12 Mb/s)
  - single-SPI (up to 12 Mb/s)
  - double-SPI (up to 2 × 12 Mb/s)
  - quad-SPI (up to 4 × 12 Mb/s)
  - IIC (up to 400 kb/s)
  - IIS (up to 12 Mb/s)
  - LIN interfaces (20kb/s)
- LEDTS in Human-Machine interface
  - up to 24 touch pads
  - drive up to 144 LEDs
- MultiCAN+, Full-CAN/Basic-CAN with 2 nodes, 32 message objects (up to 1 MBaud)

Analog Frontend Peripherals

- A/D Converters (up to 12 analog inputs)
  - 2 sample and hold stages
  - fast 12-bit ADC (up to 1.1 MS/s), adjustable gain
  - 0 V to 5.5 V input range
- Up to 8 channels out of range comparators
- Up to 4 fast analog comparators
- Temperature Sensor

Industrial Control Peripherals

- 2x4 16-bit 96 MHz CCU4 timers for signal monitoring and PWM
- 2x4 16-bit 96 MHz CCU8 timers for complex PWM, complementary high/low side switches and multi phase control
- 2x POSIF for hall and quadrature encoders, motor positioning
- 9 channel BCCU (brightness and color control) for LED lighting applications

Up to 56 Input/Output Ports

- 1.8 V to 5.5 V capable
- up to 8 high current pads (50 mA sink)

On-Chip Debug Support

- 4 breakpoints, 2 watchpoints
- ARM serial wire debug, single-pin debug interfaces

Programming Support

- Single-pin bootloader
- Secure bootstrap loader SBSL (optional)

Packages

- TSSOP-38 (9.7 × 6.4 mm^2)
- VQFN-40/48/64 (5×5/7×7/8×8 mm^2)
- LQFP-64 (12 × 12 mm^2)

Tools

- Free DAVE™ toolchain with low level drivers and apps

1.1 Device Overview

The following table lists the available features per device type for the XMC1400 series.

Table 1 Features of XMC1400 Device Types[1)]

	Features	XMC1401-Q048	XMC1401-F064	XMC1402-T038	XMC1402-Q040	XMC1402-Q048	XMC1402-Q064	XMC1402-F064	XMC1403-Q040	XMC1403-Q048	XMC1403-Q064	XMC1404-Q048	XMC1404-Q064	XMC1404-F064
	CPU frequency	48 MHz												
	Operating temperature (ambient)	-40 to 85 °C		-40 to 105 °C										
	Operating voltage	1.8 V to 5.5 V												
	Flash options (Kbytes)	64, 128	64, 128	32, 64, 128 200	32, 64, 128 200	32, 64, 128 200	64, 128 200	64, 128 200	64, 128 200	64, 128 200	64, 128 200	64, 128 200	64, 128 200	64, 128 200
	SRAM (Kbytes)	16	16	16	16	16	16	16	16	16	16	16	16	16
	MATH	-	-	1	1	1	1	1	-	-	-	1	1	1
Industrial Control	CCU4	2	2	2	2	2	2	2	2	2	2	2	2	2
	CCU8	-	-	2	2	2	2	2	-	-	-	2	2	2
	POSIF	-	-	1	1	2	2	2	-	-	-	2	2	2
	BCCU	-	-	1	1	1	1	1	-	-	-	1	1	1
Communication	USIC (modules / channels)	2 / 2	2 / 2	2 / 2	2 / 2	2 / 2	2 / 2	2 / 2	2 / 2	2 / 2	2 / 2	2 / 2	2 / 2	2 / 2
	LEDTS	3	3	-	-	-	-	-	-	-	-	3	3	3
	MultiCAN+ (nodes / MOs)	-	-	-	-	-	-	-	2 / 32	2 / 32	2 / 32	2 / 32	2 / 32	2 / 32

2 General Device Information

This section summarizes the logic symbols and package pin configurations with a detailed list of the functional I/O mapping.

2.1 Logic Symbols

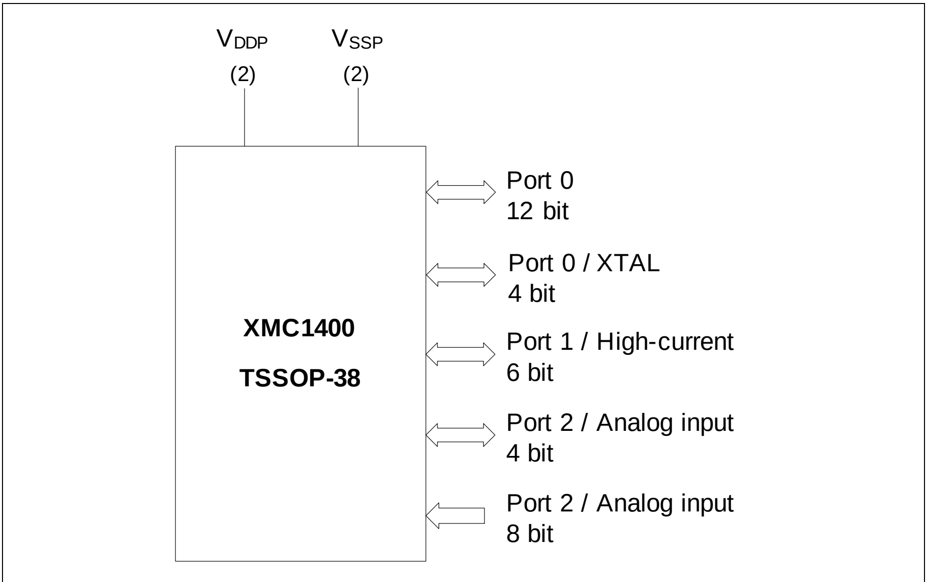

Figure 2 XMC1400 Logic Symbol for TSSOP-38-9

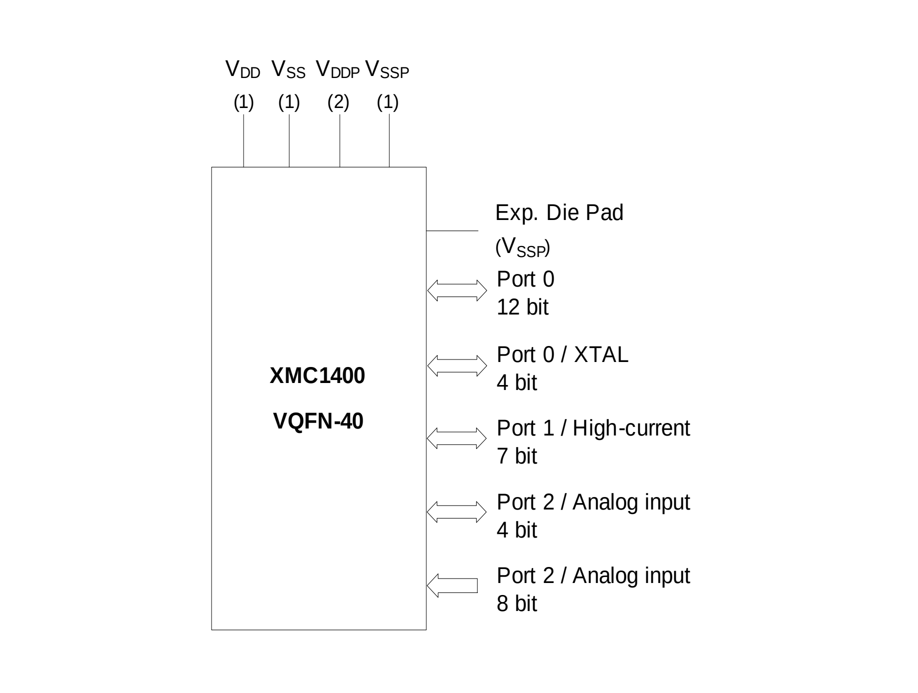

Figure 3 XMC1400 Logic Symbol for PG-VQFN-40-17

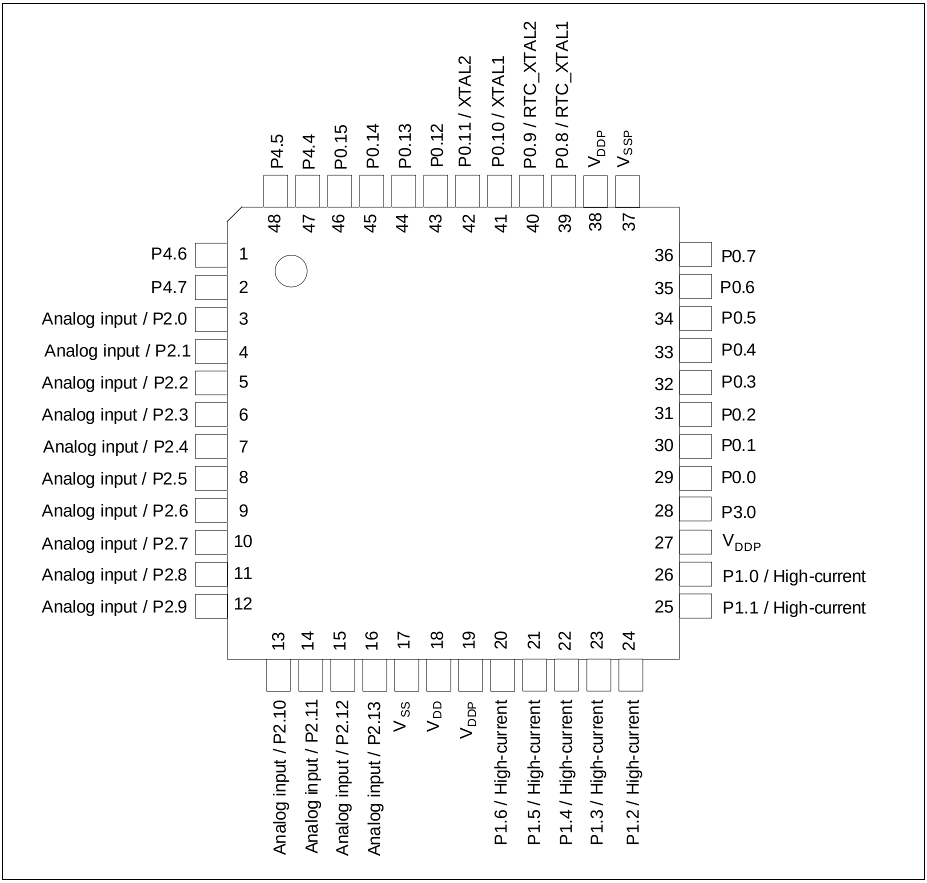

Figure 8 XMC1400 PG-VQFN-48-73 Pin Configuration (top view)

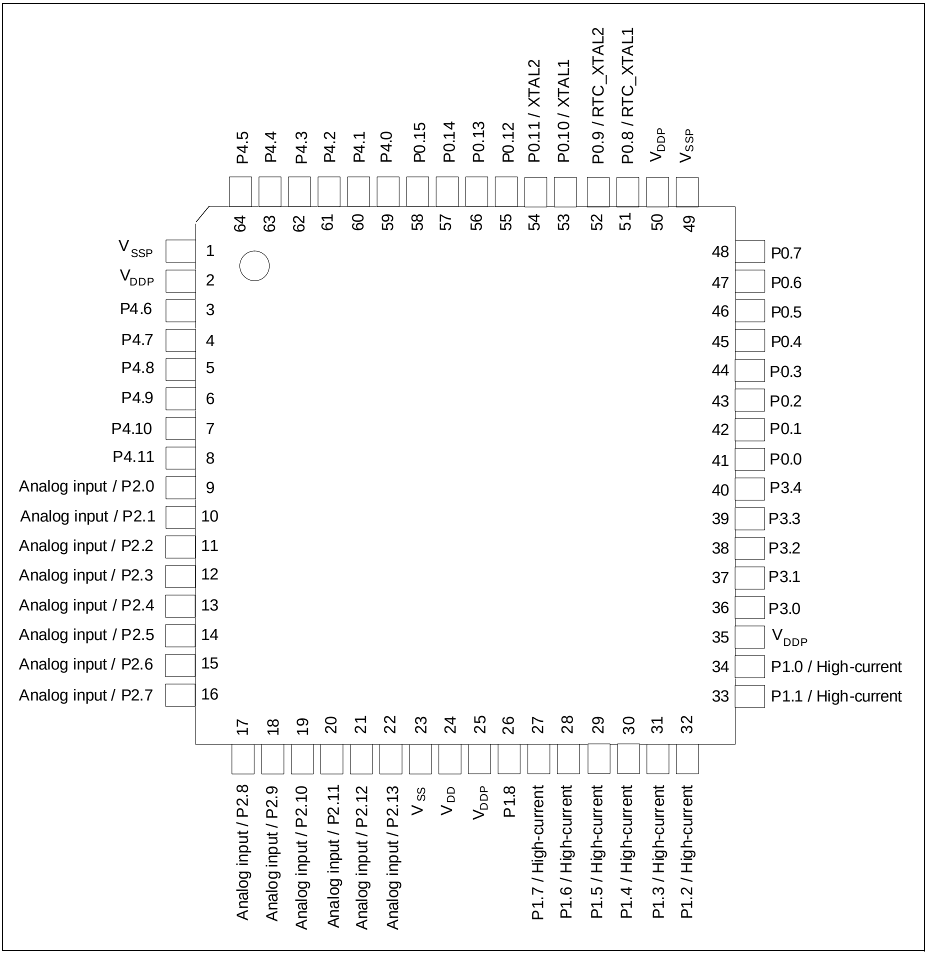

Figure 9 XMC1400 PG-LQFP-64-26 / PG-VQFN-64-6 Pin Configuration (top view)

Table 5 Package Pin Mapping (cont'd)

Function	LQFP 64, VQFN 64	VQFN 48	VQFN 40	TSSOP 38	Pad Type	Notes
P0.9/ RTC_ XTAL2	52	40	34	28	STD_INOUT /clock_O	
P0.10/ XTAL1	53	41	35	29	STD_INOUT /clock_IN	
P0.11/ XTAL2	54	42	36	30	STD_INOUT /clock_O	
P0.12	55	43	37	31	STD_INOUT	
P0.13	56	44	38	32	STD_INOUT	
P0.14	57	45	39	33	STD_INOUT	
P0.15	58	46	40	34	STD_INOUT	
P1.0	34	26	22	16	High Current	
P1.1	33	25	21	15	High Current	
P1.2	32	24	20	14	High Current	
P1.3	31	23	19	13	High Current	
P1.4	30	22	18	12	High Current	
P1.5	29	21	17	11	High Current	
P1.6	28	20	16	-	High Current	
P1.7	27	-	-	-	High Current	
P1.8	26	-	-	-	STD_INOUT	
P2.0	9	3	1	35	STD_INOUT /AN	
P2.1	10	4	2	36	STD_INOUT /AN	
P2.2	11	5	3	37	STD_IN/AN	
P2.3	12	6	4	38	STD_IN/AN	
P2.4	13	7	5	1	STD_IN/AN	
P2.5	14	8	6	2	STD_IN/AN	
P2.6	15	9	7	3	STD_IN/AN	
P2.7	16	10	8	4	STD_IN/AN	

Table 9 Port I/O Functions (cont'd)

Function	Outputs									Inputs											
	ALT1	**ALT2**	**ALT3**	**ALT4**	**ALT5**	**ALT6**	**ALT7**	**ALT8**	**ALT9**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**
P2.2										ACMP2.INN	VADC0.G0CH7		ORC0.AIN	USIC1_CH0.DX5E		USIC0_CH0.DX3A	USIC0_CH0.DX4A	USIC0_CH1.DX5A			ERU0.0B1
P2.3												VADC0.G1CH5	ORC1.AIN	USIC1_CH0.DX3E	USIC1_CH0.DX4E	USIC1_CH1.DX5C	USIC0_CH0.DX5B	USIC0_CH1.DX3C	USIC0_CH1.DX4C		ERU0.1B1
P2.4												VADC0.G1CH6	ORC2.AIN	USIC1_CH1.DX3C	USIC1_CH1.DX4C	USIC0_CH0.DX3B	USIC0_CH0.DX4B	USIC1_CH0.DX5F	USIC0_CH1.DX5B		ERU0.0A1
P2.5												VADC0.G1CH7	ORC3.AIN	USIC1_CH1.DX5D		USIC0_CH0.DX5D		USIC0_CH1.DX3E	USIC0_CH1.DX4E		ERU0.1A1
P2.6										ACMP1.INN	VADC0.G0CH0		ORC4.AIN	USIC1_CH1.DX3E	USIC1_CH1.DX4E	USIC0_CH0.DX3E	USIC0_CH0.DX4E	USIC0_CH1.DX5D			ERU0.2A1
P2.7										ACMP1.INP		VADC0.G1CH1	ORC5.AIN	USIC1_CH1.DX5E		USIC0_CH0.DX5C		USIC0_CH1.DX3D	USIC0_CH1.DX4D		ERU0.3A1
P2.8										ACMP0.INN	VADC0.G0CH1	VADC0.G1CH0	ORC6.AIN			USIC0_CH0.DX3D	USIC0_CH0.DX4D	USIC0_CH1.DX5C			ERU0.3B1
P2.9										ACMP0.INP	VADC0.G0CH2	VADC0.G1CH4	ORC7.AIN			USIC0_CH0.DX5A		USIC0_CH1.DX3B	USIC0_CH1.DX4B		ERU0.3B0
P2.10	ERU0.PDOUT1	CCU40.OUT2	ERU0.GOUT1	LEDTS1.COL4	CCU80.OUT30	ACMP0.OUT	USIC0_CH1.DOUT0		CAN.N1_TXD		VADC0.G0CH3	VADC0.G1CH2				USIC0_CH0.DX3C	USIC0_CH0.DX4C	USIC0_CH1.DX0F		CAN.N1_RXDE	ERU0.2B0
P2.11	ERU0.PDOUT0	CCU40.OUT3	ERU0.GOUT0	LEDTS1.COL3	CCU80.OUT31	USIC0_CH1.SCLKOUT	USIC0_CH1.DOUT0		CAN.N1_TXD	ACMP.REF	VADC0.G0CH4	VADC0.G1CH3						USIC0_CH1.DX0E	USIC0_CH1.DX1E	CAN.N1_RXDF	ERU0.2B1
P2.12	BCCU0.OUT3	VADC0.EMUX00	USIC1_CH0.SCLKOUT	USIC1_CH1.SCLKOUT		ACMP2.OUT	USIC1_CH1.DOUT0	LEDTS2.COL6		ACMP3.INN						USIC1_CH0.DX3A	USIC1_CH0.DX4A	USIC1_CH1.DX0C	USIC1_CH1.DX1B		ERU1.3A2
P2.13	BCCU0.OUT4	CCU40.OUT3	USIC1_CH0.MCLKOUT	CCU81.OUT31		VADC0.EMUX01	USIC1_CH1.DOUT0	CCU81.OUT33	CCU41.OUT3	ACMP3.INP						USIC1_CH0.DX5A		USIC1_CH1.DX0D			ERU1.3A3
P3.0	BCCU0.OUT0	USIC1_CH1.DOUT0	USIC1_CH1.SCLKOUT	LEDTS2.COLA	CCU80.OUT21	ACMP1.OUT	USIC1_CH0.SELO1	CCU81.OUT21	CCU41.OUT0	BCCU0.TRAPINC	CCU41.IN0AA	CCU41.IN1AA	CCU41.IN2AA	CCU41.IN3AA	CCU81.IN0AA	CCU81.IN1AA	CCU81.IN2AA	USIC1_CH1.DX0E	USIC1_CH1.DX1D	CCU81.IN3AA	ERU1.0A1
P3.1	BCCU0.OUT1	USIC1_CH1.DOUT0		LEDTS2.COL0	CCU80.OUT20	ACMP3.OUT	USIC1_CH0.SELO0	CCU81.OUT20	CCU41.OUT1								USIC1_CH0.DX2F	USIC1_CH1.DX0F			ERU1.1A1

Table 9 Port I/O Functions (cont'd)

Function	Outputs									Inputs											
	ALT1	**ALT2**	**ALT3**	**ALT4**	**ALT5**	**ALT6**	**ALT7**	**ALT8**	**ALT9**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**
P4.10		LEDTS2.LINE6	LEDTS2.COL1	LEDTS1.COL1	CCU80.OUT00	CCU40.OUT2	USIC1_CH0.SELO3	CCU81.OUT32	CCU81.OUT00	BCCU0.TRAPIND	CCU40.IN2AV	CCU41.IN2BA		CCU81.IN3AB			USIC1_CH0.DX2D	USIC1_CH1.DX5A			
P4.11		LEDTS2.LINE7	LEDTS2.COL0	LEDTS1.COL0	CCU80.OUT01	CCU40.OUT3	USIC1_CH0.SELO4	CCU81.OUT33	CCU81.OUT01		CCU40.IN3AV	CCU41.IN3BA					USIC1_CH0.DX2E	USIC1_CH1.DX3A	USIC1_CH1.DX4A		

Table 10 Hardware I/O Controlled Functions

Function	Outputs	Outputs	Inputs	Inputs	Pull Control	Pull Control	Pull Control	Pull Control
	HWO0	HWO1	HWI0	HWI1	HW0_PD	HW0_PU	HW1_PD	HW1_PU
P0.0	LEDTS0. EXTENDED7		LEDTS0.TSIN7	LEDTS0.TSIN7	Reserved for LEDTS Scheme A: pull-down disabled always	Reserved for LEDTS Scheme A: pull-down enabled always	Reserved for LEDTS Scheme B: pull-up enabled and pull-down disabled, and vice versa	
P0.1	LEDTS0. EXTENDED6		LEDTS0.TSIN6	LEDTS0.TSIN6				
P0.2	LEDTS0. EXTENDED5		LEDTS0.TSIN5	LEDTS0.TSIN5				
P0.3	LEDTS0. EXTENDED4		LEDTS0.TSIN4	LEDTS0.TSIN4				
P0.4	LEDTS0. EXTENDED3		LEDTS0.TSIN3	LEDTS0.TSIN3				
P0.5	LEDTS0. EXTENDED2		LEDTS0.TSIN2	LEDTS0.TSIN2				
P0.6	LEDTS0. EXTENDED1		LEDTS0.TSIN1	LEDTS0.TSIN1				
P0.7	LEDTS0. EXTENDED0		LEDTS0.TSIN0	LEDTS0.TSIN0				
P0.8	LEDTS1. EXTENDED0		LEDTS1.TSIN0	LEDTS1.TSIN0				
P0.9	LEDTS1. EXTENDED1		LEDTS1.TSIN1	LEDTS1.TSIN1				
P0.10	LEDTS1. EXTENDED2		LEDTS1.TSIN2	LEDTS1.TSIN2				
P0.11	LEDTS1. EXTENDED3		LEDTS1.TSIN3	LEDTS1.TSIN3				
P0.12	LEDTS1. EXTENDED4		LEDTS1.TSIN4	LEDTS1.TSIN4				
P0.13	LEDTS1. EXTENDED5		LEDTS1.TSIN5	LEDTS1.TSIN5				
P0.14	LEDTS1. EXTENDED6		LEDTS1.TSIN6	LEDTS1.TSIN6				
P0.15	LEDTS1. EXTENDED7		LEDTS1.TSIN7	LEDTS1.TSIN7				
P1.0		USIC0_CH0.DOUT0		USIC0_CH0.HWIN0	$\overline{\text{BCCU0.OUT2}}$	BCCU0.OUT2		
P1.1		USIC0_CH0.DOUT1		USIC0_CH0.HWIN1	$\overline{\text{BCCU0.OUT3}}$	BCCU0.OUT3		
P1.2		USIC0_CH0.DOUT2		USIC0_CH0.HWIN2	$\overline{\text{BCCU0.OUT4}}$	BCCU0.OUT4		

Table 10 Hardware I/O Controlled Functions

Function	Outputs	Outputs	Inputs	Inputs	Pull Control	Pull Control	Pull Control	Pull Control
	HWO0	HWO1	HWI0	HWI1	HW0_PD	HW0_PU	HW1_PD	HW1_PU
P4.4	LEDTS2. EXTENDED0		LEDTS2.TSIN0	LEDTS2.TSIN0	Reserved for LEDTS Scheme A: pull-down disabled always	Reserved for LEDTS Scheme A: pull-down enabled always	Reserved for LEDTS Scheme B: pull-up enabled and pull-down disabled, and vice versa	
P4.5	LEDTS2. EXTENDED1		LEDTS2.TSIN1	LEDTS2.TSIN1				
P4.6	LEDTS2. EXTENDED2		LEDTS2.TSIN2	LEDTS2.TSIN2				
P4.7	LEDTS2. EXTENDED3		LEDTS2.TSIN3	LEDTS2.TSIN3				
P4.8	LEDTS2. EXTENDED4		LEDTS2.TSIN4	LEDTS2.TSIN4				
P4.9	LEDTS2. EXTENDED5		LEDTS2.TSIN5	LEDTS2.TSIN5				
P4.10	LEDTS2. EXTENDED6		LEDTS2.TSIN6	LEDTS2.TSIN6				
P4.11	LEDTS2. EXTENDED7		LEDTS2.TSIN7	LEDTS2.TSIN7				

Table 16 Input/Output Characteristics (Operating Conditions apply) (cont'd)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			Min.	Max.		
Input low voltage on port pins (Large Hysteresis)	V_{ILPL}	SR	–	$0.08 \times V_{DDP}$	V	CMOS Mode (5 V, 3.3 V & 2.2 V)
Input high voltage on port pins (Large Hysteresis)	V_{IHPL}	SR	$0.85 \times V_{DDP}$	–	V	CMOS Mode (5 V, 3.3 V & 2.2 V)
Rise/fall time on High Current Pad[1]	t_{HCPR}, t_{HCPF}	CC	–	9	ns	50 pF @ 5 V[2]
			–	12	ns	50 pF @ 3.3 V[3]
			–	25	ns	50 pF @ 1.8 V[4]
Rise/fall time on Standard Pad[1]	t_R, t_F	CC	–	12	ns	50 pF @ 5 V[5]
			–	15	ns	50 pF @ 3.3 V[6].
			–	31	ns	50 pF @ 1.8 V[7].
Input Hysteresis on port pin except P2.3 - P2.9[8]	HYS	CC	$0.08 \times V_{DDP}$	–	V	CMOS Mode (5 V), Standard Hysteresis
			$0.03 \times V_{DDP}$	–	V	CMOS Mode (3.3 V), Standard Hysteresis
			$0.02 \times V_{DDP}$	–	V	CMOS Mode (2.2 V), Standard Hysteresis
			$0.5 \times V_{DDP}$	$0.75 \times V_{DDP}$	V	CMOS Mode(5 V), Large Hysteresis
			$0.4 \times V_{DDP}$	$0.75 \times V_{DDP}$	V	CMOS Mode(3.3 V), Large Hysteresis
			$0.2 \times V_{DDP}$	$0.65 \times V_{DDP}$	V	CMOS Mode(2.2 V), Large Hysteresis

Table 17 ADC Characteristics (Operating Conditions apply)[1)] (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Maximum sample rate in 8-bit mode[4)]	f_{C8} CC	–	–	f_{ADC} / 38.5	–	1 sample pending
		–	–	f_{ADC} / 54.5	–	2 samples pending
RMS noise[5)]	EN_{RMS} CC	–	1.5	–	LSB 12	DC input, SHSCFG.AREF = 00_B, GNCTRxz.GAINy = 00_B (unity gain), V_{DD} = 5.0 V, V_{AIN} = 2.5 V, 25°C
DNL error	EA_{DNL} CC	–	±2.0	–	LSB 12	
INL error	EA_{INL} CC	–	±4.0	–	LSB 12	
Gain error with external reference	EA_{GAIN} CC	–	±0.5	–	%	SHSCFG.AREF = 00_B (calibrated)
Gain error with internal reference[6)]	EA_{GAIN} CC	–	±3.6	–	%	SHSCFG.AREF = $1X_B$ (calibrated), -40°C - 110°C
		–	±2.0	–	%	SHSCFG.AREF = $1X_B$ (calibrated), 0°C - 85°C
Offset error	EA_{OFF} CC	–	±8.0	–	mV	Calibrated, V_{DD} = 5.0 V

1) The parameters are defined for ADC clock frequencies f_{SH} = 32 MHz for the full supply range, and f_{SH} = 48 MHz at V_{DD_int}, V_{DD_ext} = 5 V. Usage of any other frequencies may affect the ADC performance.

2) The alternate reference ground connection is separate for each converter. This mode, therefore, provides the lowest noise impact.

3) No pending samples assumed, excluding sampling time and calibration.

4) Includes synchronization and calibration (average of gain and offset calibration).

5) This parameter can also be defined as an SNR value: SNR[dB] = 20 × log(A_{MAXeff} / N_{RMS}).
With $A_{MAXeff} = 2^N / 2$, SNR[dB] = 20 × log (2048 / N_{RMS}) [N = 12].
N_{RMS} = 1.5 LSB12, therefore, equals SNR = 20 × log (2048 / 1.5) = 62.7 dB.

6) Includes error from the reference voltage.

3.2.3 Out of Range Comparator (ORC) Characteristics

The Out-of-Range Comparator (ORC) triggers on analog input voltages (V_{AIN}) above V_{DDP} on selected input pins (ORCx.AIN) and generates a service request trigger (ORCx.OUT).

Note: These parameters are not subject to production test, but verified by design and/or characterization.

Table 18 Out of Range Comparator (ORC) Characteristics (Operating Conditions apply; V_{DDP} = 3.0 V - 5.5 V; C_L = 0.25pF)

Parameter	Symbol		Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
DC Switching Level	V_{ODC}	CC	–	–	180	mV	$V_{AIN} \geq V_{DDP} + V_{ODC}$
Hysteresis	V_{OHYS}	CC	15	–	54	mV	
Always detected Overvoltage Pulse	t_{OPDD}	CC	103	–	–	ns	$V_{AIN} \geq V_{DDP}$ + 150 mV
			88	–	–	ns	$V_{AIN} \geq V_{DDP}$ + 350 mV
Never detected Overvoltage Pulse	t_{OPDN}	CC	–	–	21	ns	$V_{AIN} \geq V_{DDP}$ + 150 mV
			–	–	11	ns	$V_{AIN} \geq V_{DDP}$ + 350 mV
Detection Delay	t_{ODD}	CC	39	–	132	ns	$V_{AIN} \geq V_{DDP}$ + 150 mV
			31	–	121	ns	$V_{AIN} \geq V_{DDP}$ + 350 mV
Release Delay	t_{ORD}	CC	44	–	240	ns	$V_{AIN} \leq V_{DDP}$; V_{DDP} = 5 V
			57	–	340	ns	$V_{AIN} \leq V_{DDP}$; V_{DDP} = 3.3 V
Enable Delay	t_{OED}	CC	–	–	300	ns	ORCCTRL.ENORCx = 1

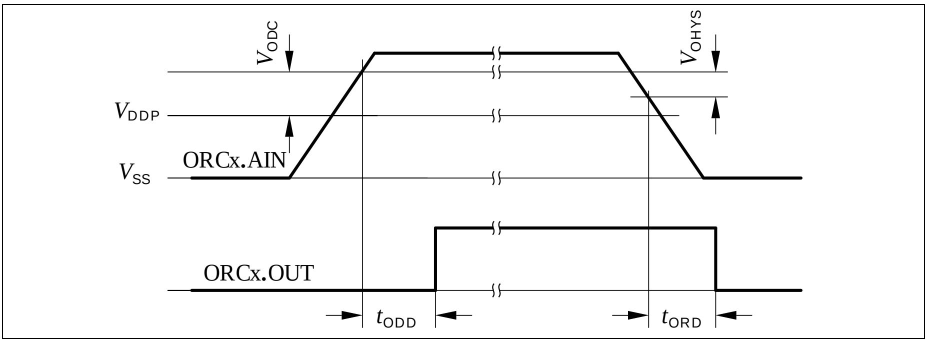

Figure 13 ORCx.OUT Trigger Generation

3.2.5 Temperature Sensor Characteristics

Note: These parameters are not subject to production test, but verified by design and/or characterization.

Table 20 Temperature Sensor Characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Measurement time	t_M CC	–	–	10	ms	
Temperature sensor range	T_{SR} SR	-40	–	115	°C	
Sensor Accuracy[1]	T_{TSAL} CC	-6	–	6	°C	T_J > 20°C
		-10	–	10	°C	0°C ≤ T_J ≤ 20°C
		–	-/+8	–	°C	T_J < 0°C
Start-up time	t_{TSST} SR	–	–	15	µs	

1) The temperature sensor accuracy is independent of the supply voltage.

Table 24 provides the active current consumption of some modules operating at 5 V power supply at 25 °C. The typical values shown are used as a reference guide on the current consumption when these modules are enabled.

Table 24 Typical Active Current parameter table

Active Current Consumption	Symbol	Limit Values	Unit	Test Condition
		Typ.		
Baseload current	I_{CPUDDC}	4.14	mA	Modules including Core, SCU, PORT, memories, ANATOP[1)]
VADC and SHS	I_{ADCDDC}	3.73	mA	Set CGATCLR0.VADC to 1[2)]
USICx	$I_{USIC0DDC}$	1.35	mA	Set CGATCLR0.USIC0 to 1[3)]
CCU4x	$I_{CCU40DDC}$	0.99	mA	Set CGATCLR0.CCU40 to 1[4)]
CCU8x	$I_{CCU80DDC}$	1.00	mA	Set CGATCLR0.CCU80 to 1[5)]
POSIFx	$I_{PIF0DDC}$	1.05	mA	Set CGATCLR0.POSIF0 to 1[6)]
LEDTSx	$I_{LTSxDDC}$	1.14	mA	Set CGATCLR0.LEDTSx to 1[7)]
BCCU0	$I_{BCCU0DDC}$	0.29	mA	Set CGATCLR0.BCCU0 to 1[8)]
MATH	$I_{MATHDDC}$	0.50	mA	Set CGATCLR0.MATH to 1[9)]
WDT	I_{WDTDDC}	0.03	mA	Set CGATCLR0.WDT to 1[10)]
RTC	I_{RTCDDC}	0.01	mA	Set CGATCLR0.RTC to 1[11)]
MultiCAN	$I_{MCANDDC}$	1.38	mA	Set CGATCLR0.MCAN0 to 1[12)]

1) Baseload current is measured with device running in user mode, MCLK=PCLK=48 MHz, with an endless loop in the flash memory. The clock to the modules stated in CGATSTAT0 are gated.
2) Active current is measured with: module enabled, MCLK=48 MHz, running in auto-scan conversion mode
3) Active current is measured with: module enabled, each of the 2 USIC channels sending alternate messages at 57.6 kbaud every 200 ms
4) Active current is measured with: module enabled, MCLK=PCLK=48 MHz, 1 CCU4 slice for PWM switching at 20kHz with duty cycle varying at 10%-90%, 1 CCU4 slice in capture mode for reading period and duty cycle
5) Active current is measured with: module enabled, MCLK=PCLK=48 MHz, 3 CCU8 slices with PWM frequency at 20kHz and a period match interrupt used to toggle duty cycle between 10% and 90%
6) Active current is measured with: module enabled, MCLK=48 MHz, PCLK=96 MHz, hall sensor mode
7) Active current is measured with: module enabled, MCLK=48 MHz, 1 LED column, 6 LED/TS lines, Pad Scheme A with large pad hysteresis config, time slice duration = 1.048 ms
8) Active current is measured with: module enabled, MCLK=48 MHz, PCLK=96MHz, FCLK=0.8 MHz, Normal mode (BCCU clock = FCLK/4), 4 BCCU Channels with packers enabled and 1 Dimming Engine, change color or dim every 1s
9) Active current is measured with: module enabled, MCLK=48 MHz, PCLK=96 MHz, tangent calculation in while loop; CORDIC circular rotation, no keep, autostart; 32-by-32 bit signed DIV, autostart, DVS right shift by 11

3.2.8 Flash Memory Parameters

Note: These parameters are not subject to production test, but verified by design and/or characterization.

Table 25 Flash Memory Parameters

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Erase time per page / sector	t_{ERASE} CC	6.8	7.1	7.6	ms	
Program time per block	t_{PSER} CC	102	152	204	µs	
Wake-Up time	t_{WU} CC	–	32.2	–	µs	
Read time per word	t_a CC	–	50	–	ns	
Data Retention Time	t_{RET} CC	10	–	–	years	Max. 100 erase / program cycles
Flash Wait States [1)]	$N_{WSFLASH}$ CC	0	0	0		f_{MCLK} = 8 MHz
		0	1	1		f_{MCLK} = 16 MHz
		1	2	2		f_{MCLK} = 32 MHz
		2	2	3		f_{MCLK} = 48 MHz
Erase Cycles	N_{ECYC} CC	–	–	$5*10^4$	cycles	Sum of page and sector erase cycles
Total Erase Cycles	N_{TECYC} CC	–	–	$2*10^6$	cycles	

1) Flash wait states are automatically inserted by the Flash module during memory read when needed. Typical values are calculated from the execution of the Dhrystone benchmark program.

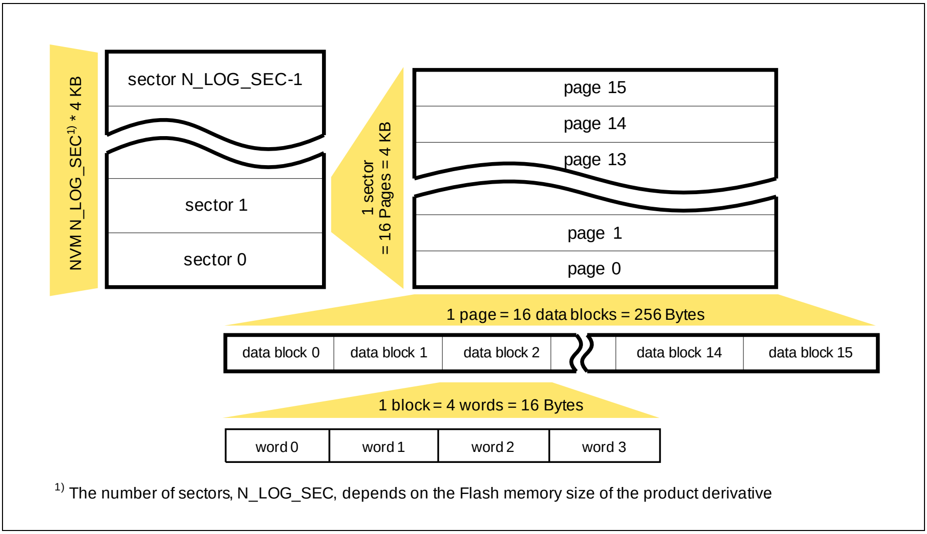

Figure 19 Logical Structure of the Flash

Table 26 Power-Up and Supply Threshold Parameters (Operating Conditions apply) (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
V_{DDP} brownout reset voltage	V_{DDPBO} CC	1.55	1.62	1.75	V	calibrated, before user code starts running
V_{DDP} voltage to ensure defined pad states	V_{DDPPA} CC	–	1.0	–	V	
Start-up time from power-on reset	t_{SSW} SR	–	260	–	µs	Time to the first user code instruction[3)]
BMI program time	t_{BMI} SR	–	8.25	–	ms	Time taken from a user-triggered system reset after BMI installation is is requested

1) A capacitor of at least 100 nF has to be added between V_{DDP} and V_{SSP} to fulfill the requirement as stated for this parameter.

2) Valid for a 100 nF buffer capacitor connected to supply pin where current from capacitor is forwarded only to the chip. A larger capacitor value has to be chosen if the power source sink a current.

3) This values does not include the ramp-up time. During startup firmware execution, MCLK is running at 48 MHz and the clocks to peripheral as specified in register CGATSTAT0 are gated.

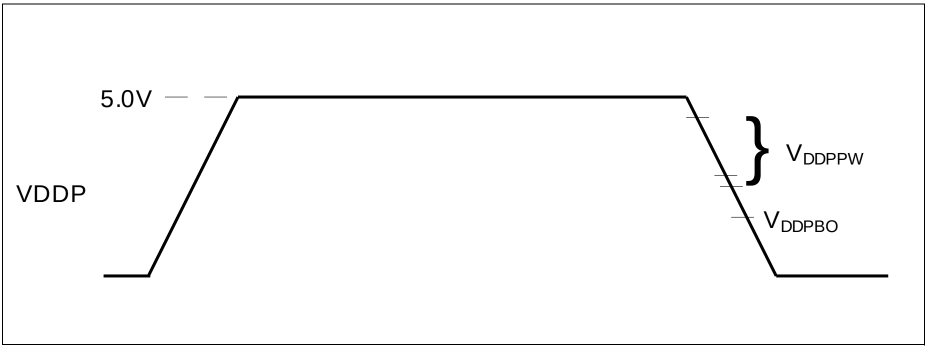

Figure 23 Supply Threshold Parameters

The difference between junction temperature and ambient temperature is determined by
$\Delta T = (P_{INT} + P_{IOSTAT} + P_{IODYN}) \times R_{\Theta JA}$

The internal power consumption is defined as
$P_{INT} = V_{DDP} \times I_{DDP}$ (switching current and leakage current).

The static external power consumption caused by the output drivers is defined as
$P_{IOSTAT} = \Sigma((V_{DDP}\text{-}V_{OH}) \times I_{OH}) + \Sigma(V_{OL} \times I_{OL})$

The dynamic external power consumption caused by the output drivers (P_{IODYN}) depends on the capacitive load connected to the respective pins and their switching frequencies.

If the total power dissipation for a given system configuration exceeds the defined limit, countermeasures must be taken to ensure proper system operation:

- Reduce V_{DDP}, if possible in the system
- Reduce the system frequency
- Reduce the number of output pins
- Reduce the load on active output drivers